

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NSC Co., Ltd.	12/15/2009
RECEIVING PARTY DATA	
Name:	Kurosaki Technologies, LLC
Street Address:	2711 Centerville Road, Suite 400
City:	Wilmington
State/Country:	DELAWARE
Postal Code:	19808
PROPERTY NUMBERS Total: 4	
Property Type	Number
Patent Number:	6383891
Patent Number:	6844777
Patent Number:	6937092
Patent Number:	7224294
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	Laura Chu

OP \$160.00 6383891

Total Attachments: 5
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EXHIBIT B

ASSIGNMENT OF PATENT RIGHTS

For good and valuable consideration, the receipt of which is hereby acknowledged, NSC Co., Ltd., a Japanese company having an office at Shin Kojimachi Bldg., 8F, 3-3, Kojimachi 4-chome, Chiyoda-ku, Tokyo 102-0083, Japan ("*Assignor*"), does hereby sell, assign, transfer, and convey unto Kurosaki Technologies, LLC, a Delaware limited liability company, having an office at 2711 Centerville Road, Suite 400, Wilmington, Delaware, 19808, U.S.A. ("*Assignee*"), or its designees, all right, title, and interest that exist today and may exist in the future in and to all of the following (collectively, the "*Patent Rights*"), including:

(a) each of the provisional patent applications, patent applications and patents listed in the **Attachment B** hereto ("*Listed Patents*"),

(b) all patents or patent applications (i) to which any of the foregoing directly or indirectly claim priority, (ii) for which any of the foregoing directly or indirectly forms a basis for priority, (iii) that were co-owned patent applications that incorporate by reference, or are incorporated by reference into, any of the foregoing, (iv) that are reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, or divisions of any of the foregoing, and/or (v) that are foreign patents, patent applications and counterparts to any of the foregoing, including certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants or issuances, and any of the foregoing in (i)-(v) whether or not expressly listed as Listed Patents below and whether or not abandoned, rejected, or the like;

(c) inventions, invention disclosures, and discoveries described in any of the Listed Patents and/or any of the foregoing category (b) to the extent that any such inventions, invention disclosures, and discoveries (i) are included in any claim in the Listed Patents and/or any of the foregoing category (b), (ii) are subject matter capable of being reduced to a patent claim in any reissue or reexamination proceedings brought on any of the Listed Patents and/or any of the foregoing category (b), and/or (iii) could have been and/or could be included as a claim in any continuations, continuations in part, continuing prosecution applications, requests for continuing examinations and/or divisions of the Listed Patents and/or any of the foregoing category (b);

(d) rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections or other governmental grants or issuances of any type related to the any of the foregoing categories (a), (b) and/or (c), including, without limitation, under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement or understanding;

(e) causes of action (whether currently pending, filed, or otherwise) and other enforcement rights, including, without limitation, all rights under the Listed Patents and/or under or on account of any

of the foregoing categories (b), (c) and/or (d) to (i) damages, (ii) injunctive relief and (iii) other remedies of any kind for past, current and future infringement; and

(f) all rights to collect royalties and other payments under or on account of any of the Listed Patents or any of the foregoing categories (b) through (e).

Assignor represents, warrants and covenants that:

(1) Assignor has the full power and authority, and has obtained all third party consents, approvals and/or other authorizations required to enter into this Assignment of Patent Rights and to carry out its obligations hereunder, including the assignment of the Patent Rights to Assignee; and

(2) Assignor owns all right, title, and interest to the Patent Rights, including, without limitation, all right, title, and interest to sue for infringement of the Patent Rights. Assignor has obtained and properly recorded previously executed assignments for the Patent Rights as necessary to fully perfect its rights and title therein in accordance with governing law and regulations in each respective jurisdiction. The Patent Rights are free and clear of all liens, claims, mortgages, security interests or other encumbrances, and restrictions. There are no actions, suits, investigations, claims or proceedings threatened, pending or in progress relating in any way to the Patent Rights. There are no existing contracts, agreements, options, commitments, proposals, bids, offers, or rights with, to, or in any person to acquire any of the Patent Rights.

Assignor hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents, certificates of invention, utility models or other governmental grants or issuances that may be granted upon any of the Patent Rights in the name of Assignee, as the assignee to the entire interest therein.

The terms and conditions of this Assignment of Patent Rights will inure to the benefit of Assignee, its successors, assigns, and other legal representatives and will be binding upon Assignor, its successors, assigns, and other legal representatives.

[Signature Page to Follow]

IN WITNESS WHEREOF this Assignment of Patent Rights is executed at Tokyo, Japan on this 15 day of December, 2009.

ASSIGNOR

NSC Co., Ltd.

By: Hajime Momose

Name: Hajime Momose

Title: President and Representative Liquidator

(Signature MUST be attested)

ATTESTATION OF SIGNATURE PURSUANT TO 28 U.S.C. §1746

The undersigned witnessed the signature of Hajime Momose to the above Assignment of Patent Rights on behalf of NSC Co., Ltd. and makes the following statements:

1. I am over the age of 18 and competent to testify as to the facts in this Attestation block if called upon to do so.
2. Hajime Momose is personally known to me (or proved to me on the basis of satisfactory evidence) and appeared before me on December 15, 2009 to execute the above Assignment of Patent Rights on behalf of NSC Co., Ltd.
3. Hajime Momose subscribed to the above Assignment of Patent Rights on behalf of NSC Co., Ltd.

I declare under penalty of perjury under the laws of the United States of America that the statements made in the three (3) numbered paragraphs immediately above are true and correct.

EXECUTED on December 15, 2009 (date)

By: Rumi Kawasaki

Print Name: Rumi Kawasaki

Attachment B

Listed Patents

Patent No./ Appln. No.	Country	Title	Inventors	Filing Date
CNZL97199490.0	CN	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
JP3983300	JP	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
KR10-0368946	KR	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
6,383,891	US	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
HK1023649	HK	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
DE69737939.6	DE	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
FR0949668	FR	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
GB0949668	GB	Method for forming bump and semiconductor device	Okamoto, Akira	10/29/1997
TW101969	TW	A method of forming a bump, and semiconductor device	Okamoto, Akira	11/4/1997
JP2001-205634	JP	Audio amplifier	Kitamura, Mamoru	7/6/2001
TW201276	TW	Audio amplifier	Kitamura, Mamoru	7/1/2002
6,844,777	US	Audio amplifier	Kitamura, Mamoru	7/4/2002
6,937,092	US	Audio amplifier	Kitamura, Mamoru	7/4/2002
JP2001-173884	JP	Compressor device and method, decompressing device and method, compressing/decompressing system, program, record medium	Koyanagi, Yukio	6/8/2001
TW193431	TW	Compression device and method, decompression device and method, compression/decompression system, program, recording medium	Koyanagi, Yukio	5/16/2002
CNZL02802615.2	CN	Compressing device and method, decompressing device and method, compressing, decompressing system, program, record medium	Koyanagi, Yukio	5/23/2002

Patent No./ Appln. No.	Country	Title	Inventors	Filing Date
CN200610108752.5	CN	Compressing device and method, decompressing device and method	Koyanagi, Yukio	5/23/2002
7,224,294	US	Compressing device and method, decompressing device and method, compressing/decompressing system, program, record medium	Koyanagi, Yukio	5/23/2002

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